

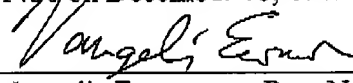
DEC 18 2003

**OFFICIAL** PATENTDOCKET: CU-2417  
Customer No. 26530**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application: Takahiro IJIMA et al.	]	
	]	
Serial No.: 09/736,864	]	GRP ART UNIT : 2815
	]	
Filed: December 14, 2000	]	Ex.: CHU, C.
	]	
For: INTERCONNECTION SUBSTRATE	]	
HAVING METAL COLUMNS COVERED BY A	]	
RESIN FILM AND MANUFACTURING	]	
METHOD THEREOF	]	

**Certification under 37 C.F.R. §1.8(a)**

I hereby certify that this correspondence is being transmitted by facsimile to the United States Patent and Trademark Office at the following facsimile number: (703) 872-9306, to the attention of Examiner C. Chu, and addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on December 18, 2003.

  
Vangelis Economou, Reg. No. 32,341

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT UNDER 37 CFR § 1.116**

Sir:

In response to the Official Action dated October 21, 2003, please amend the above-identified application as follows:

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in this application: